NTC Inrush Current Limiters

Mounting instructions

Date: November 2015
1 Soldering

1.1 Leaded NTC thermistors

Leaded thermistors comply with the solderability requirements specified by CECC.

When soldering, care must be taken that the NTC thermistors are not damaged by excessive heat. The following maximum temperatures, maximum time spans and minimum distances have to be observed:

<table>
<thead>
<tr>
<th></th>
<th>Dip soldering</th>
<th>Iron soldering</th>
</tr>
</thead>
<tbody>
<tr>
<td>Bath temperature</td>
<td>max. 260 °C</td>
<td>max. 360 °C</td>
</tr>
<tr>
<td>Soldering time</td>
<td>max. 4 s</td>
<td>max. 2 s</td>
</tr>
<tr>
<td>Distance from thermistor</td>
<td>min. 6 mm</td>
<td>min. 6 mm</td>
</tr>
</tbody>
</table>

Under more severe soldering conditions the resistance may change.

Solderability (test to IEC 60068-2-20)
Preconditioning: Immersion into flux F-SW 32.
Evaluation criterion: Wetting of soldering areas \( \geq 95\% \).

<table>
<thead>
<tr>
<th>Solder</th>
<th>Bath temperature (°C)</th>
<th>Dwell time (s)</th>
</tr>
</thead>
<tbody>
<tr>
<td>SnAg (3.0 ... 4.0), Cu (0.5 ... 0.9)</td>
<td>245 ±3</td>
<td>3</td>
</tr>
</tbody>
</table>

1.1.1 Resistance to soldering heat (test to IEC 60068-2-20)
Preconditioning: Immersion into flux F-SW 32.

<table>
<thead>
<tr>
<th>Solder</th>
<th>Bath temperature (°C)</th>
<th>Dwell time (s)</th>
</tr>
</thead>
<tbody>
<tr>
<td>SnAg (3.0 ... 4.0), Cu (0.5 ... 0.9)</td>
<td>260 –5</td>
<td>10</td>
</tr>
</tbody>
</table>
1.1.2 Wave soldering

Temperature characteristic at component terminal with dual wave soldering

![Temperature characteristic graph]

2 Robustness of terminations

The leads meet the requirements of IEC 60068-2-21. They may not be bent closer than 4 mm from the solder joint on the thermistor body or from the point at which they leave the feed-throughs. During bending, any mechanical stress at the outlet of the leads must be removed. The bending radius should be at least 0.75 mm.

Tensile strength: Test Ua1:
Leads

<table>
<thead>
<tr>
<th>Diameter (mm)</th>
<th>Tensile Strength (N)</th>
</tr>
</thead>
<tbody>
<tr>
<td>0.50 &lt; Ø ≤ 0.80</td>
<td>10.0 N</td>
</tr>
<tr>
<td>0.80 &lt; Ø ≤ 1.25</td>
<td>20.0 N</td>
</tr>
</tbody>
</table>

Bending strength: Test Ub:
Two 90°-bends in opposite directions at a weight of 0.25 kg.

Torsional strength: Test Uc: severity 2
The lead is bent by 90° at a distance of 6 to 6.5 mm from the thermistor body.
The bending radius of the leads should be approx. 0.75 mm. Two torsions of 180° each (severity 2).
When subjecting leads to mechanical stress, the following should be observed:

**Tensile stress on leads**
During mounting and operation tensile forces on the leads are to be avoided.

**Bending of leads**
Bending of the leads directly on the thermistor body is not permissible.

A lead may be bent at a minimum distance of twice the wire's diameter +2 mm from the solder joint on the thermistor body. During bending the wire must be mechanically relieved at its outlet. The bending radius should be at least 0.75 mm.

**Twisting of leads**
The twisting (torsion) by 180° of a lead bent by 90° is permissible at 6 mm from the bottom of the thermistor body.

3 **Sealing and potting**
When thermistors are sealed, potted or overmolded, there must be no mechanical stress caused by thermal expansion during the production process (curing / overmolding process) and during later operation. The upper category temperature of the thermistor must not be exceeded. Ensure that the materials used (sealing / potting compound and plastic material) are chemically neutral.

4 **Cleaning**
If cleaning is necessary, mild cleaning agents such as ethyl alcohol and cleaning gasoline are recommended. Cleaning agents based on water are not allowed. Ultrasonic cleaning methods are permissible.

5 **Storage**
In order to maintain their solderability, thermistors must be stored in a non-corrosive atmosphere. Humidity, temperature and container materials are critical factors.
The components should be left in the original packing. Touching the metallization of unsoldered thermistors may change their soldering properties.

Storage temperature: $-25 \, ^\circ C$ up to $45 \, ^\circ C$
Max. relative humidity (without condensation): $<95\%$, maximum 30 days per annum
Solder the thermistors listed in this data book after shipment from EPCOS within the time specified:
Leaded components: 24 months